

ITC 2022 Poster Submission Is Open

The poster submission deadline for ITC 2022 has been extended to June 27, 2022. To submit a poster proposal, please prepare a one- or two-page write-up about the poster work. The ITC poster write-up should follow the same IEEE conference paper format where the templates for Word and Latex can be found at IEEE site:

<https://www.ieee.org/conferences/publishing/templates.html>.

The Call-for-Papers (including the posters) is attached in the next page.

Submission To Tracks By Invitation Only

If a track is marked as "By Invitation Only", please **do not** submit to this track, unless you have received specific instruction to invite you to submit a paper to this track. These tracks are dedicated for special sessions decided by the Program Chair.

**Regular Paper Submission Has
Closed!**



2022 INTERNATIONAL TEST CONFERENCE

SEPTEMBER 26 - 29, 2022

Disneyland, CA, USA

Call for Papers

The International Test Conference (ITC) is the world's premier venue dedicated to the electronic test of devices, boards and systems—covering the complete cycle from design verification, design-for-test, design-for-manufacturing, silicon debug, manufacturing test, system test, diagnosis, reliability and failure analysis, and back to process and design improvement.

Emerging technologies in design and manufacturing will require new test solutions. Artificial Intelligence (AI) and the need for trustworthy devices are providing both new challenges and new opportunities for off-chip and on-chip test. At the same time, more stringent quality requirements, especially in automotive applications, are requiring more efficient test, debug, monitoring, and repair techniques that can transfer to the field.

Authors are invited to submit original, unpublished papers describing recent work in the field of testing and testable design. Of particular interest are works dedicated to the topics listed on the right and/or works focused on special tracks such as Automotive, 5G/6G, AI, or Security. Authors are also invited to submit practical, industry oriented papers. A special **industrial case-study track** is dedicated to papers that enable others to learn best industrial practices. Submissions simultaneously under review or accepted by another conference, symposium or journal, will be summarily rejected. The submission is through the EasyChair paper submission system.

Submissions must include:

- Title of paper.
- Name, affiliation, e-mail address of each author.
- The corresponding author(s). ITC will communicate with the corresponding author(s).
- One or two topic(s) from the topic list, or a description of your topic.
- An electronic copy of a complete paper of 6~10 pages for regular papers (including Industrial case-study papers) or 3~5 pages for short Industrial Practices papers.
- An abstract of 35 words or less to be entered online.

ITC maintains a competitive selection process for technical papers. Submissions must clearly describe the status of the reported work, its contribution, novelty and/or significance. Supporting data, results (priority is often given to papers with results from real designs) and conclusions, and references to prior work must also be included. ITC does not accept submissions that do not meet the specified criteria.

Paper title/abstract due: March 14, 2022
Paper final PDF due: March 28, 2022
Author notification: June 6, 2022
Final manuscript due: July 11, 2022

Authors are also invited to submit a one- or two-page poster proposal. Posters are a useful way of presenting late-breaking results, getting feedback on an innovative method, or participating without having to write a full paper. Acceptance as a poster does not preclude submission of a more complete work as an ITC paper in 2023. Additional information on poster submissions will be provided on the ITC web page.

Poster submission deadline: ~~June 13, 2022~~ **June 27, 2022**
Author notification: July 7, 2022

Test Week tutorial and workshop proposals are also welcomed. Deadlines and other information about proposals can be obtained from TTTC at: <http://tab.computer.org/ttc>

For detailed information about the submission process, requirements and deadlines, the selection process and any other questions regarding the program itself or contact information, please consult the ITC web site at <http://www.itctestweek.org>.

ITC invites submissions on the latest advances in test, validation, diagnosis and security of IPs, ICs, boards and systems.

Topics of interest include, but not limited to:

3D/2.5D Test
5G/6G Test
Adaptive Test in Practice
AI/Machine Learning in Test
ATE/Probe Card Design
Automotive Test
Advances in Boundary Scan
Built-In Self-Test
Data Driven Test Methods
Defect-oriented Testing
Design for Test
DFM and Test
Diagnosis
Economics of Test
End-to-End Data Analysis
End-to-End System Security
Emerging Defect Mechanisms
Field Monitoring, Test, & Debug
Hardware Security and Trust
IoT Testing
Jitter, High-Speed I/O and RF Test
Known-Good-Die Test
Memory Test and Repair
MEMS Testing
Mixed-Signal and Analog Test
New Technologies and Test
Online Test
Pre-Silicon/Post-Silicon Verification
Power Issues in Test
Protocol-aware Test
Quantum Device Testing
Reliability and Resiliency
SoC/SiP/NoC Test
Silicon Debug
Simulation and Emulation
System Test (Applications)
System Test (Hardware/Software)
Test Compression
Test-to-Design Feedback
Test Escape Analysis
Test Flow Optimizations
Test Generation and Validation
Test Resource Partitioning
Test Standards
Testing High Speed Optics/Photonics
Timing Test
Yield Analysis and Optimization